2025년 2월 14일(금), 15:10-17:10
Room H(루비 I), 5층

Q. Metrology, Inspection, Analysis, and Yield Enhancement 분과

O74_[FH3-Q] Metrology, Inspection, Analysis, and Yield Enhancement II

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초청 FH3-Q-1 15:10-15:40	A Study on Improving Accuracy of Optical 3-D Profile Measurement Using in-Wafer Gradient of Dimensionally Reduced Ellipsometry Spectrum Hyeong-Jun Jeong[1], Minkyu Kim[2], Sungyoon Ryu[1], Taejin Kim[1], Gwanghun Jung[1], Young-Seok Kim[1], and Younghoon Sohn[1] [1]Metrology & Inspection Technology Team, Samsung Electronics, Ltd., [2]CSE Team, Samsung Electronics Ltd
초청 FH3-Q-2 15:40-16:10	Matching Technology of Metrology Tools for FAB Process Yong Woo Jung, Yu Seong Gim, and Hee Ju Park SK hynix
초청 FH3-Q-3 16:10-16:40	Development of Various EUV Sources for Application in Actinic Tools for EUV Masks Dong Gun Lee ESOL. Inc.
FH3-Q-4 16:40-16:55	Development of Stack Die MI Measurement Methodology for the Unrivaled HBM Memory Hye Yun Seong, Young Hoon Lee, and Sung Hyun Yoon SK hynix Inc.
FH3-Q-5 16:55-17:10	The Industry's First Study on Inline Mass Measurement Methods for Chip-Level Warpage to Yield Improvement of HBM Sang-Yeop Lee[1], Sang yup Lee[2], In Tae Whoang[1], Jung Hwi Kim[1], Min Yeop Lee[1], and Young Hoon Lee[1] [1]SK Hynix Inc., [2]Georgia Institute of Technology